


APPLICATION DATA SHEET

Electronic Version v14

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Title of Invention	ELECTRICAL PACKAGE STRUCTURE INCLUDING CHIP WITH POLYMER THEREON		
Application Type : regular, utility Attorney Docket Number : 13365-US-PA			
Correspondence address: Customer Number: 31561			
			
Inventors Information:			
<u>Inventor 1:</u>			
Applicant Authority Type:	Inventor		
Citizenship:	TW		
Name prefix:	Mr.		
Given Name:	Kai-Kuang		
Family Name:	Ho		
Residence:			
City of Residence:	Hsinchu City		
Country of Residence:	TW		
Address-1 of Mailing Address:	18F-4, No. 17, Lane 175, Wuling Rd.		
Address-2 of Mailing Address:			
City of Mailing Address:	Hsinchu City		
State of Mailing Address:			
Postal Code of Mailing Address:	300		
Country of Mailing Address:	TW		
Phone:			
Fax:			
E-mail:			
<u>Inventor 2:</u>			
Applicant Authority Type:	Inventor		
Citizenship:	TW		
Name prefix:	Mr.		
Given Name:	Kuo-Ming		
Family Name:	Chen		

Residence:

City of Residence: Hsinchu County
Country of Residence: TW
Address-1 of Mailing Address: No. 16-1, Dalin Village, Beipu Township
Address-2 of Mailing Address:
City of Mailing Address: Hsinchu County
State of Mailing Address:
Postal Code of Mailing Address: 314
Country of Mailing Address: TW
Phone:
Fax:
E-mail:

Attorney Information:

practitioner(s) at Customer Number:

31561



as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.